REMARKS

In the above referenced Office Action, the Examiner divided the claims into the following groups:

I. Claims 1-13, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes a non-capacitive detection device for the first surface, classified in class 73, subclass 105;

II. Claims 14-16, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes at least one of a contact probe or radiation receiver as a topographical feature detector for the first surface and a support member that supports the substrate without contacting the conductive structures located on the second surface, classified in class 73, subclass 105;

III. Claims 17-24, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes at least one of a contact probe or radiation receiver as a topographical feature detector for the first surface, classified in class 73, subclass 105;

IV. Claims 25-31 and 82-87, drawn to an apparatus and method for detecting characteristics of a microelectronic substrate that utilizes a roughness detector comprised of a contact probe and an actuator connected to at least one of the roughness detector and the support member to move at least one of the two, classified in class 73, subclass 105;

V. Claims 32-37 and 88-93, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes a roughness detector comprised of a radiation receiver and an actuator connected to at least one of the roughness detector and the support member to move at least one of the two, classified in class 73, subclass 105;
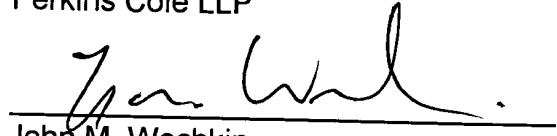
VI. Claims 38, 39 and 45-48, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes at least one of a contact probe or radiation receiver as a topographical feature detector for the first surface and first and second detectors proximate the second surface of the substrate, classified in class 73, subclass 105;

VII. Claims 40-44, drawn to an apparatus for detecting characteristics of a microelectronic substrate that utilizes a first topography detection means that detects at least one of roughness and thickness variation of a first surface of the substrate and second topography detection means to detect a characteristic of raised conductive structures present on the second surface of the substrate, classified in class 73, subclass 105;

VIII. Claims 49-62, drawn to a method of processing a microelectronic substrate, classified in class 73, subclass 105;

IX. Claims 63-77, drawn to a method for detecting characteristics of a microelectronic substrate having a first surface that has features that do not include conductive connection structures, classified in class 73, subclass 105;

X. Claims 78-81, drawn to a method in a computer for detecting characteristics of a microelectronic substrate, classified in class 73, subclass 105;

XI. Claims 94-97, drawn to a method for detecting characteristics of a microelectronic substrate, classified in class 73, subclass 105;

In response, the applicants elect Group I without traverse. Non-elected claims 14-97 have been canceled without prejudice to requesting consideration of these claims upon allowance of a generic claim, or pursuing these claims in a divisional, continuation, continuation-in-part or other application.

Upon allowance of the generic claims, applicants request consideration of claims to additional species which are written in dependent form or which otherwise include all the limitations of the allowed generic claims.

No fees are believed due with this communication. However, the Commissioner is hereby authorized and requested to charge any deficiency in fees herein to Deposit Account No. 50-0665.

Respectfully submitted,
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